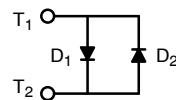
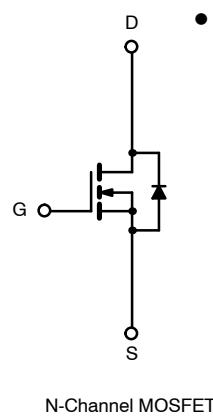
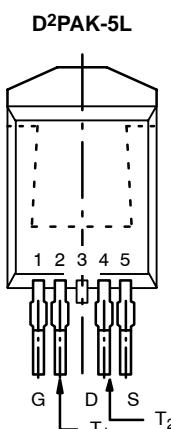


N-Channel 40-V (D-S) MOSFET with Sensing Diode

PRODUCT SUMMARY		
$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
40	0.0045 @ $V_{GS} = 10$ V	60 ^a
	0.0065 @ $V_{GS} = 4.5$ V	20 ^a



Ordering Information: SUM60N04-05LT

FEATURES

- TrenchFET® Power MOSFETs Plus Temperature Sensing Diode
- 175°C Junction Temperature
- New Low Thermal Resistance Package

APPLICATIONS

- Automotive
- Industrial

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 175^\circ\text{C}$) ^d	I_D	60 ^a	A
		60 ^a	
Pulsed Drain Current	I_{DM}	250	A
Continuous Diode Current (Diode Conduction) ^d	I_S	60 ^a	
Avalanche Current	I_{AR}	60 ^a	mJ
Repetitive Avalanche Energy ^b	E_{AR}	180	
Maximum Power Dissipation ^a	P_D	200 ^c	W
		3.75 ^d	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 175	°C

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Junction-to-Ambient ^d	R_{thJA}	40	°C/W
Junction-to-Case		0.75	

Notes

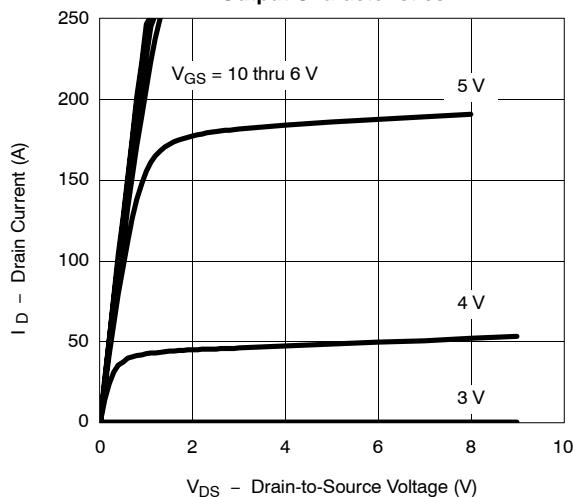
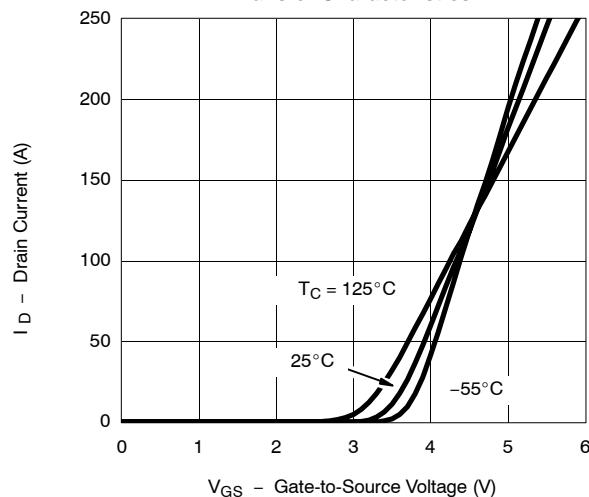
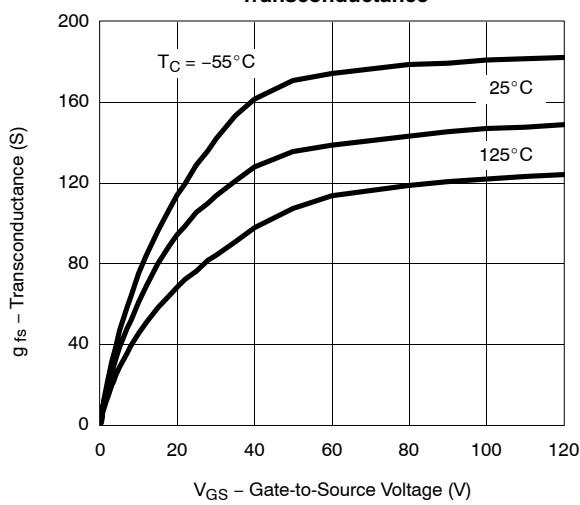
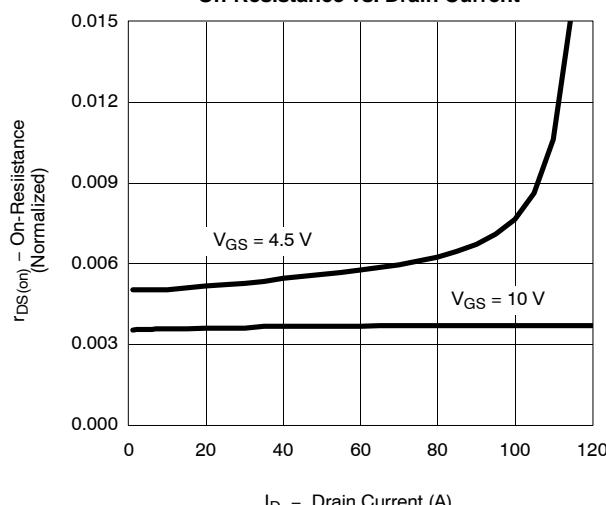
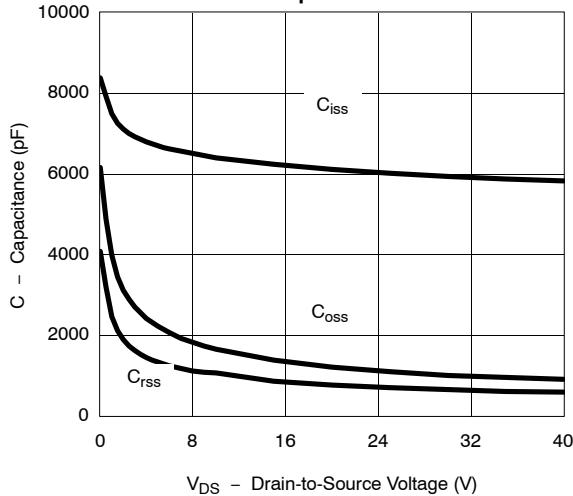
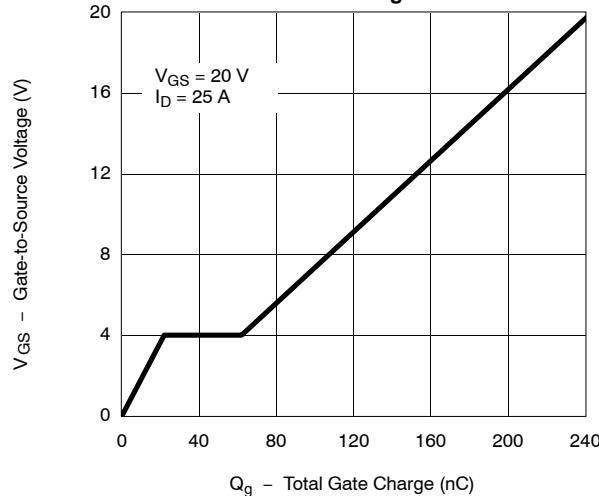
- a. Package limited.
- b. Duty cycle $\leq 1\%$.
- c. See SOA curve for voltage derating.
- d. When mounted on 1" square PCB (FR-4 material).

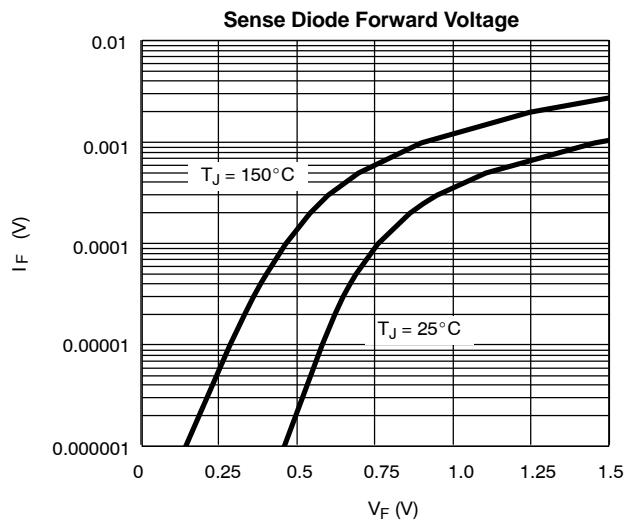
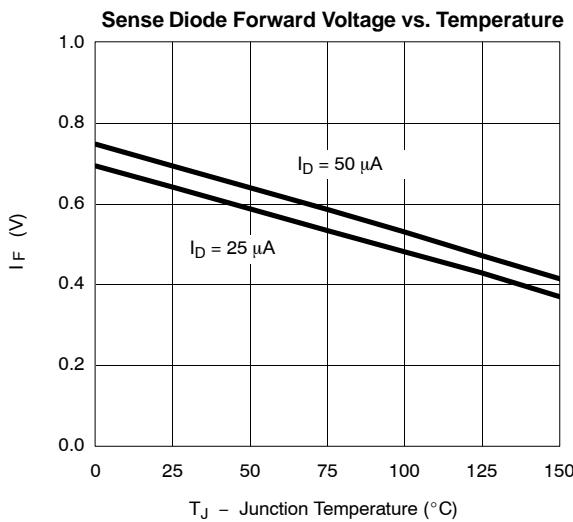
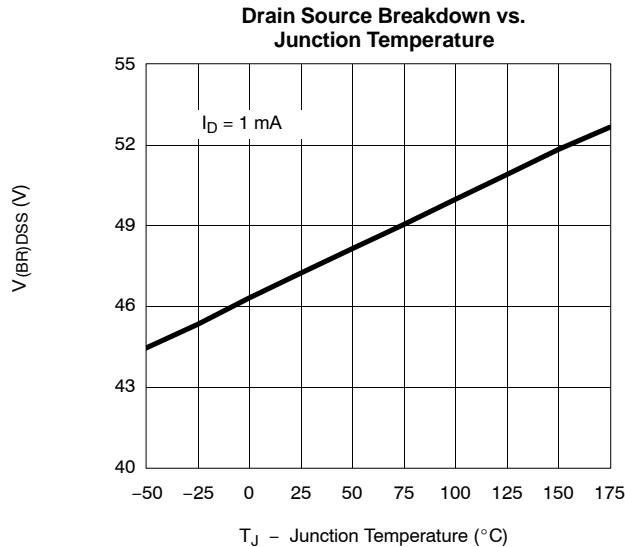
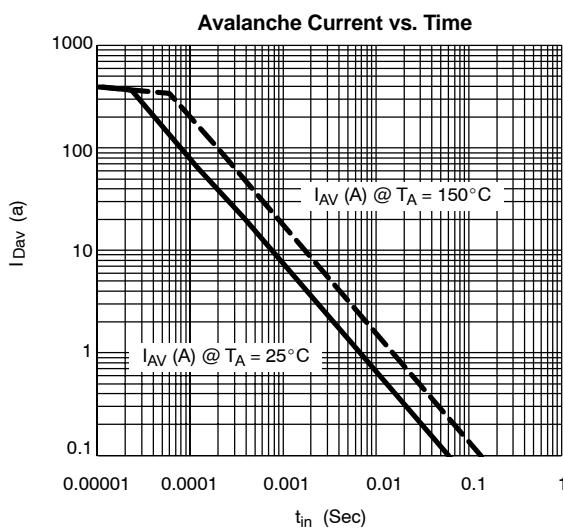
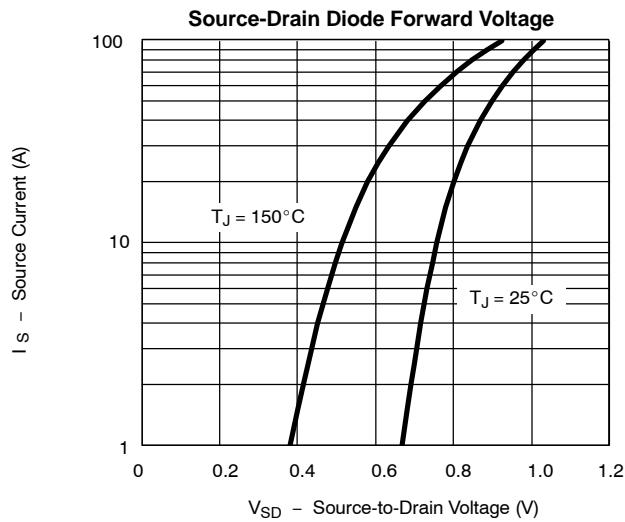
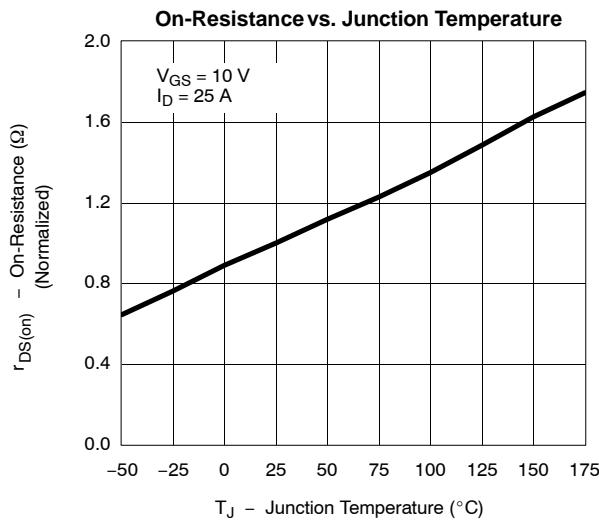
MOSFET SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

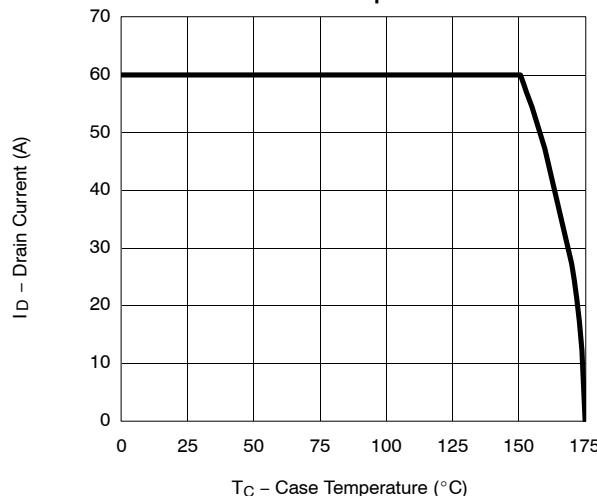
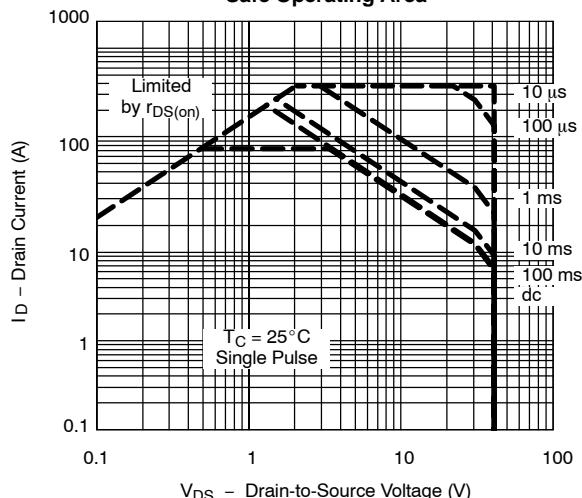
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1		3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$			1	
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125^\circ\text{C}$			50	
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 175^\circ\text{C}$			500	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			A
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}, I_D = 60 \text{ A}$		0.0035	0.0045	
		$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0051	0.0065	
		$V_{GS} = 10 \text{ V}, I_D = 60 \text{ A}, T_J = 125^\circ\text{C}$			0.0069	
		$V_{GS} = 10 \text{ V}, I_D = 60 \text{ A}, T_J = 175^\circ\text{C}$			0.0086	
Sense Diode Forward Voltage	V_{FD1} and V_{FD2}	$I_F = 50 \mu\text{A}$	655		715	
		$I_F = 25 \mu\text{A}$	600		660	
Sense Diode Forward Voltage Increase	ΔV_F	From $I_F = 25 \mu\text{A}$ to $I_F = 50 \mu\text{A}$	30		80	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15 \text{ V}, I_D = 20 \text{ A}$		35		S
Dynamic^b						
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		6000		
Output Capacitance	C_{oss}			1100		
Reversen Transfer Capacitance	C_{rss}			700		pF
Total Gate Charge ^c	Q_g	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}$		130		
Gate-Source Charge ^c	Q_{gs}			25		
Gate-Drain Charge ^c	Q_{gd}			40		nC
Turn-On Delay Time ^c	$t_{d(\text{on})}$	$V_{DD} = 20 \text{ V}, R_L = 0.8 \Omega$ $I_D \approx 25 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		15	20	
Rise Time ^c	t_r			80	120	
Turn-Off Delay Time ^c	$t_{d(\text{off})}$			100	150	
Fall Time ^c	t_f			100	150	ns
Source-Drain Diode Ratings and Characteristics ($T_C = 25^\circ\text{C}$)^b						
Continuous Current	I_s				60	
Pulsed Current	I_{SM}				200	A
Forward Voltage ^a	V_{SD}	$I_F = 60 \text{ A}, V_{GS} = 0 \text{ V}$		1.0	1.5	V
Reverse Recovery Time	t_{rr}	$I_F = 60 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$		60	90	ns
Peak Reverse Recovery Current	$I_{RM(\text{REC})}$			2.1	4	A
Reverse Recovery Charge	Q_{rr}			0.065	0.18	μC

Notes:

- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)
Output Characteristics

Transfer Characteristics

Transconductance

On-Resistance vs. Drain Current

Capacitance

Gate Charge


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

THERMAL RATINGS
**Maximum Avalanche and Drain Current
vs. Case Temperature**

Safe Operating Area

Normalized Thermal Transient Impedance, Junction-to-Case
